

N-Channel Enhancement Mode Field Effect Transistor

● **Features**

20V/6A

$R_{DS(ON)} = 21m\Omega @ V_{GS} = 4.5V$

$R_{DS(ON)} = 34m\Omega @ V_{GS} = 2.5V$

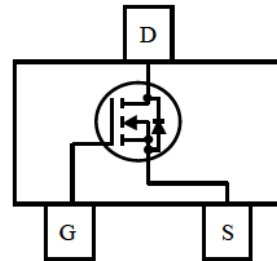
SOT23 Package

● **General Description**

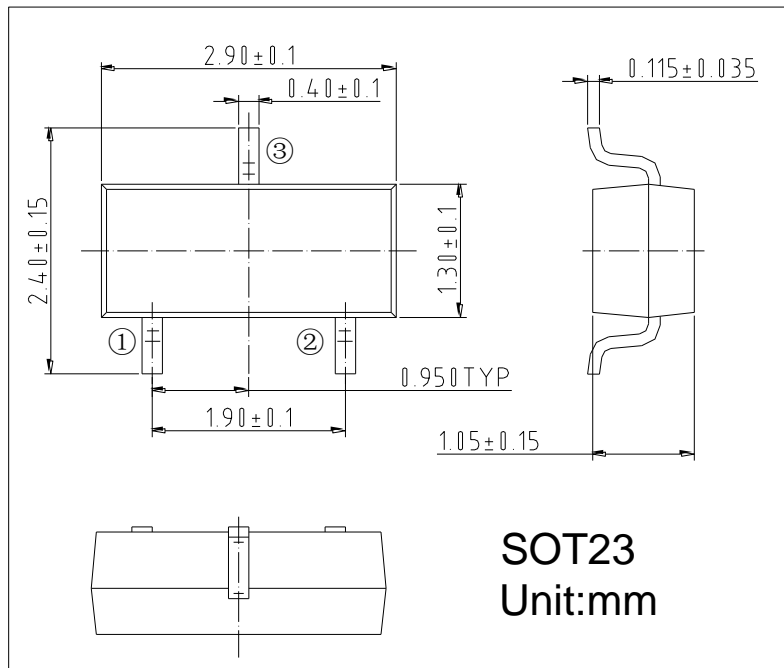
The CE2300 uses advanced trench technology to provide excellent $R_{DS(ON)}$, low gate charge and operation with gate voltages as low as 1.8V. This device is suitable for use as a load switch or in PWM applications.

● **Pin Configurations**

See Diagram below (top view)



● **Package Information**



● **Absolute Maximum Ratings @ $T_A=25^\circ C$ unless otherwise noted**

Parameter	Symbol	Ratings	Unit
Drain-Source Voltage	V_{DSS}	20	V
Gate-Source Voltage	V_{GSS}	± 12	V
Drain Current (Continuous)	I_D	$T_A=25^\circ C$	6
		$T_A=70^\circ C$	5
			A

Drain Current (Pulse)		I_{DM}	20	A
Power Dissipation	$T_A=25^{\circ}\text{C}$	P_D	1	W
Operating Temperature/ Storage Temperature		T_J/T_{STG}	-55~150	$^{\circ}\text{C}$

● **Electrical Characteristics** @ $T_A=25^{\circ}\text{C}$ unless otherwise noted

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
Static						
Drain-Source Breakdown Voltage	$V_{(BR)DSS}$	$V_{GS} = 0\text{V}, I_D=250\mu\text{A}$	20	--	--	V
Zero Gate Voltage Drain Current	I_{DSS}	$V_{DS} = 20\text{V}, V_{GS} = 0\text{V}$	--	--	1	μA
Gate Threshold Voltage	$V_{GS(TH)}$	$V_{GS}=V_{DS}, I_{DS}=250\mu\text{A}$	0.4	0.9	1.2	V
Gate Leakage Current	I_{GSS}	$V_{GS}=\pm 12\text{V}, V_{DS}=0\text{V}$	--	--	100	nA
Drain-Source On-state Resistance	$R_{DS(on)}$	$V_{GS} = 4.5\text{V}, I_D = 6\text{A}$	--	21	28	m Ω
		$V_{GS} = 2.5\text{V}, I_D = 5.2\text{A}$	--	34	45	m Ω
Forward Transconductance	g_{FS}	$V_{DS}=10\text{V}, I_D=6\text{A}$	--	5	--	S
Diode Forward Voltage	V_{SD}	$I_{SD}=1.7\text{A}, V_{GS}=0\text{V}$	--	0.8	1.2	V
Maximum Body-Diode Continuous Current	I_S		--	--	1.7	A
Switching						
Total Gate Charge	Q_g	$V_{GS}=4.5\text{V}, V_{DS}=10\text{V}, I_D=6\text{A}$	--	7.7	--	nC
Gate-Source Charge	Q_{GS}		--	3.2	--	nC
Gate-Drain Charge	Q_{GD}		--	2.1	--	nC
Turn-on Delay Time	$t_{d(on)}$	$V_{DS} = 10\text{V}, I_D = 1\text{A},$ $V_{GS} = 4.5\text{V}, R_G = 6\Omega$	--	78.7	--	ns
Turn-on Rise Time	t_r		--	128	--	ns
Turn-off Delay Time	$t_{d(off)}$		--	453	--	ns
Turn-off Fall Time	t_f		--	80.9	--	ns
Dynamic						
Input Capacitance	C_{iss}	$V_{DS} = 15\text{V}, V_{GS} = 0\text{V}, f = 1.0\text{MHz}$	--	574	--	pF
Output Capacitance	C_{oss}		--	70	--	pF
Reverse Transfer Capacitance	C_{rss}		--	60	--	pF

A: The value of $R_{\theta JA}$ is measured with the device mounted on 1in² FR-4 board with 2oz. Copper, in a still air environment with $T_A=25^{\circ}\text{C}$. The value in any given application depends on the user's specific board design.

B: Repetitive rating, pulse width limited by junction temperature.

C: The current rating is based on the $t \leq 10\text{s}$ junction to ambient thermal resistance rating.

● **Typical Performance Characteristics**

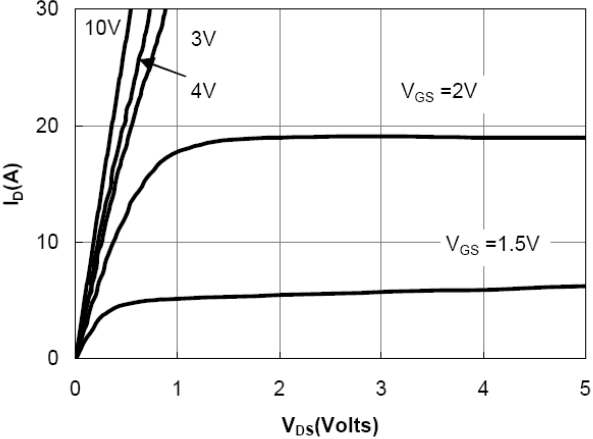


Figure 1: On-Regions Characteristic CS

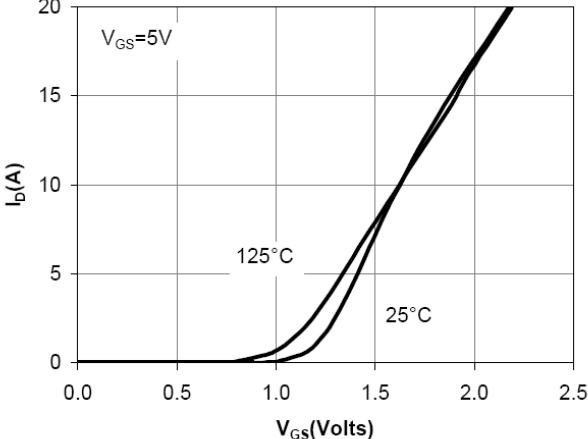


Figure 2: Transfer Characteristics

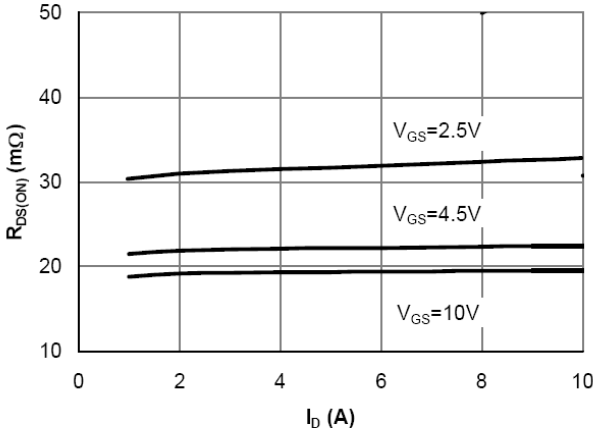


Figure 3: On-Resistance vs. Drain Current and Gate Voltage

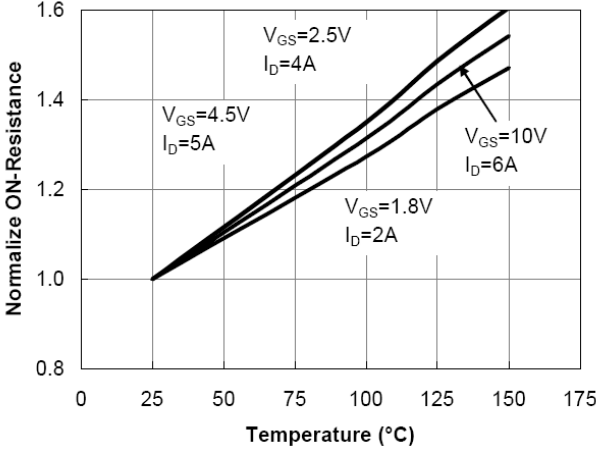


Figure 4: On-Resistance vs. Junction Temperature

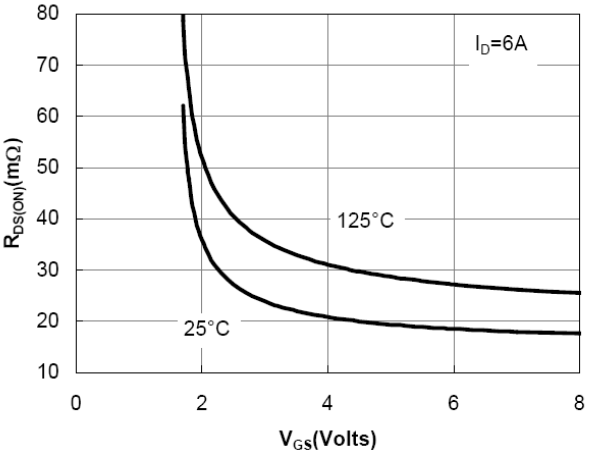


Figure 5: On-Resistance vs. Gate-Source Voltage

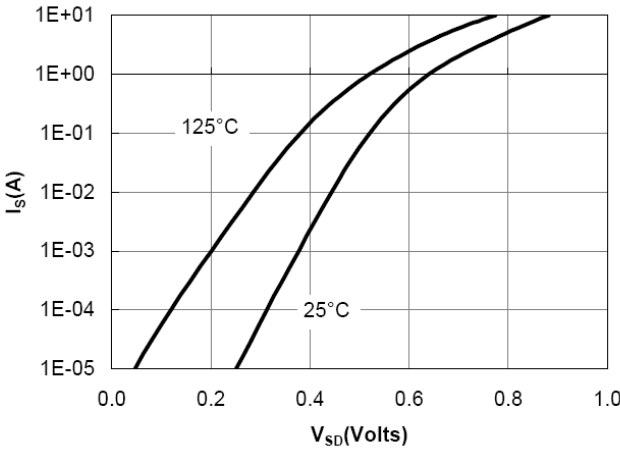


Figure 6: Body-Diode Characteristics

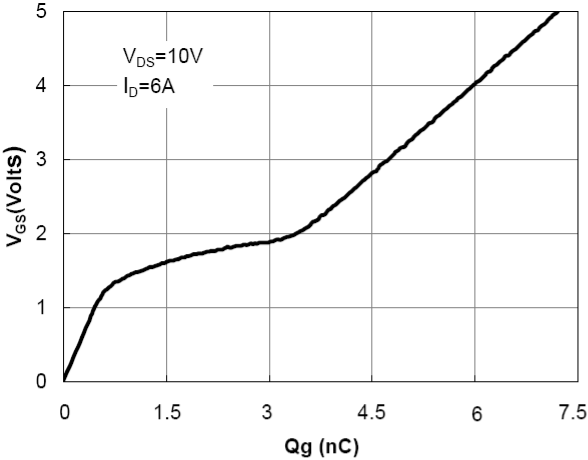


Figure 7: Gate-Charge Characteristics

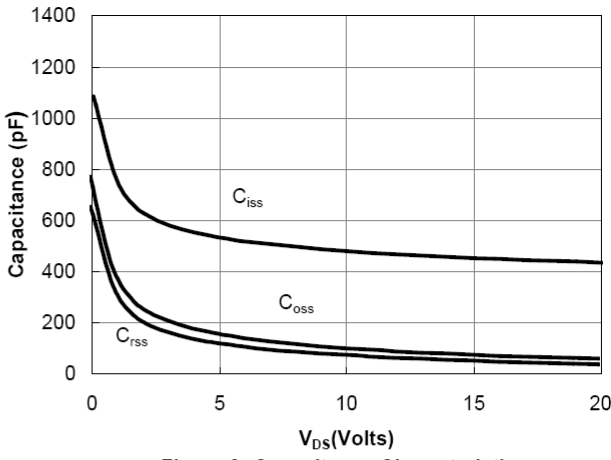


Figure 8: Capacitance Characteristics

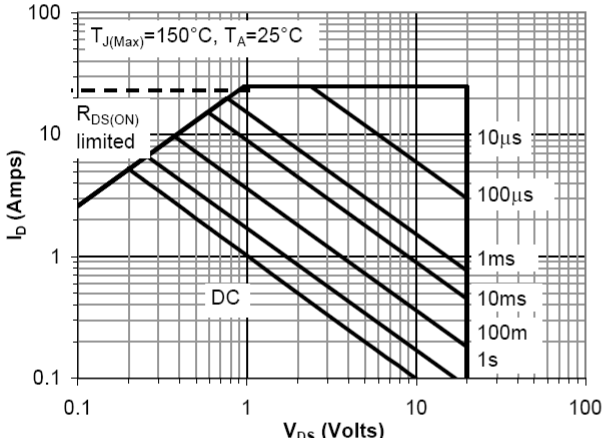


Figure 9: Maximum Forward Biased Safe Operating Area

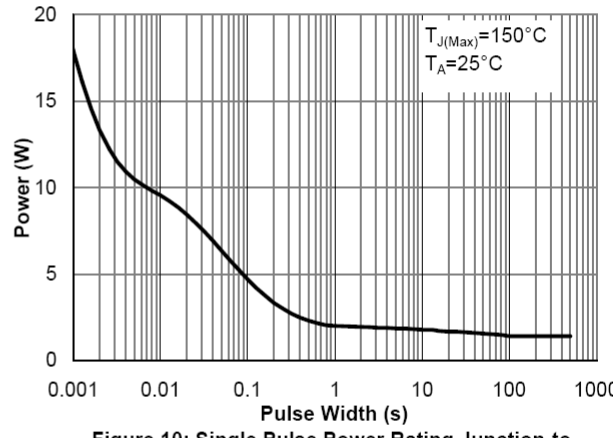


Figure 10: Single Pulse Power Rating Junction-to-Ambient

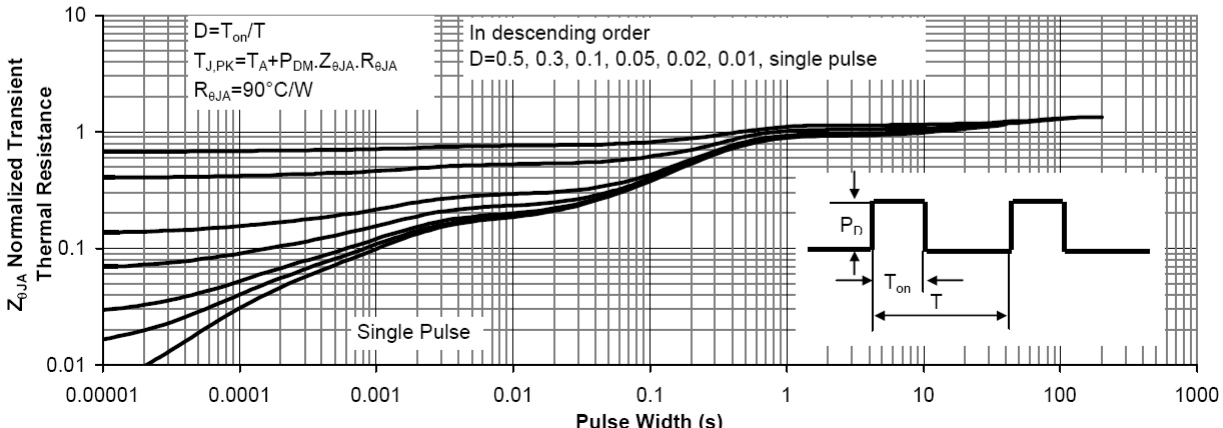


Figure 11: Normalized Maximum Transient Thermal Impedance